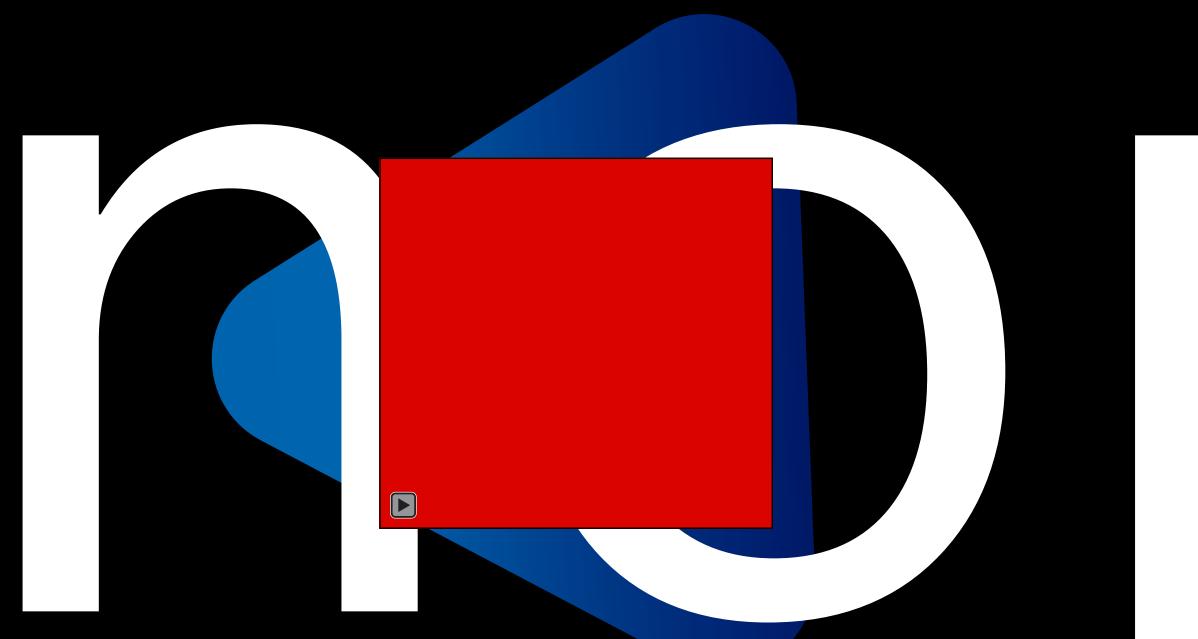
Nice to meet

you

V N a n o c e l l © 2 0 2 4



and not for the first time.



Ţ









Ţ

The industry must reduce silver consumption to meet projected wafer production levels. The ultimate goal is to transition to copper-based metallization.





Avoid oxidation

Enable low-temperature copper processing



The Copper Challenge

Ę

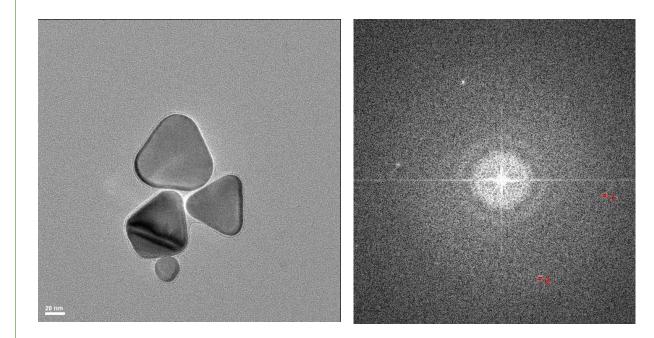
The Solution

Copper Nanoparticles



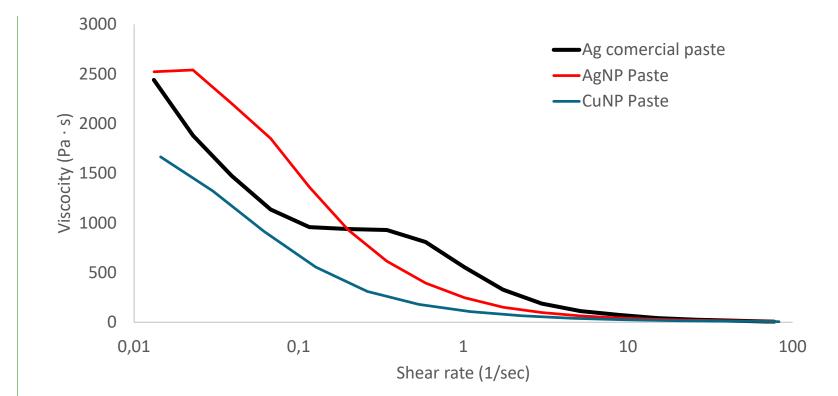
The Slow Oxidation Process Enables a Wider Processing Window at the Factory and Printing Level

- Our single-crystal nanoparticles offer superior oxidation resistance
- PVN produces its own Sicrys[™] copper nanoparticles using an environmentally friendly process producing nanoparticles with d₅₀ = 40 nm

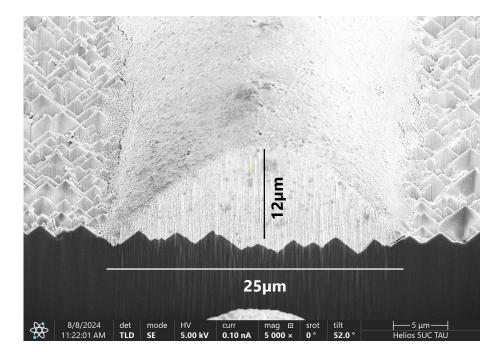


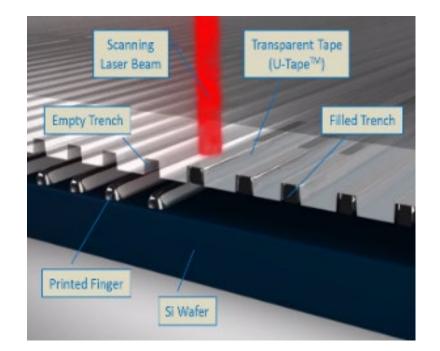


Similar Rheological Properties of Silver and Copper Nanoparticles



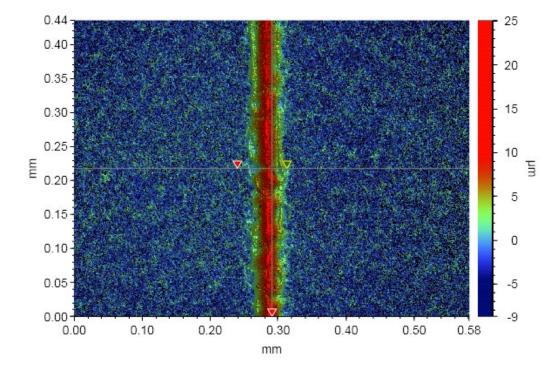
Printing 25 µm Copper Lines with PTP Technology

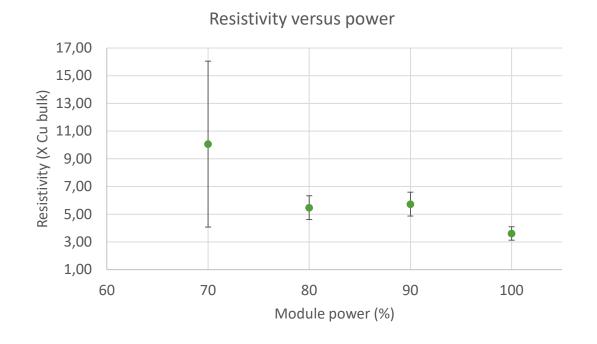






Initial Results of Laser Sintering Copper Paste

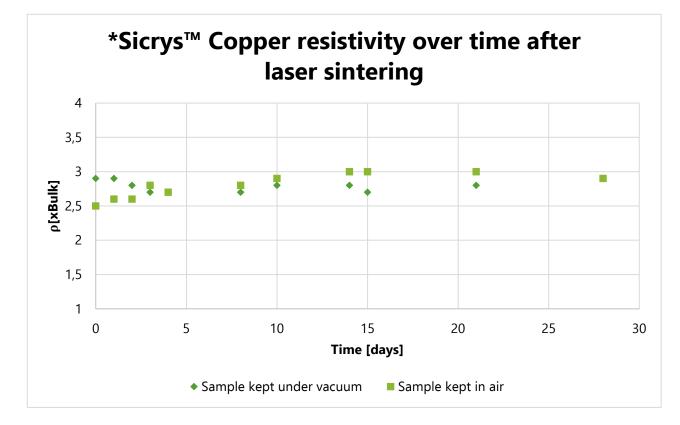


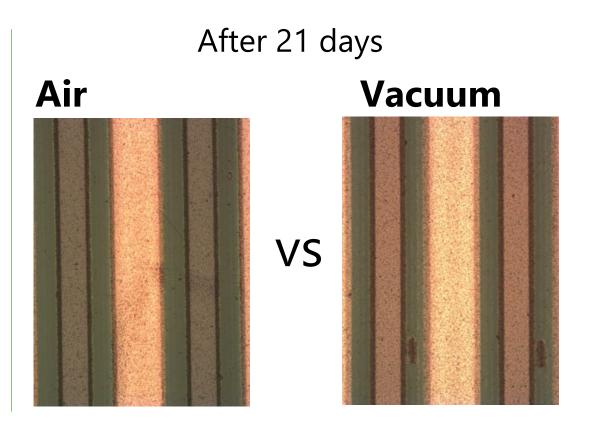






Initial Results of Laser Sintering Copper Paste



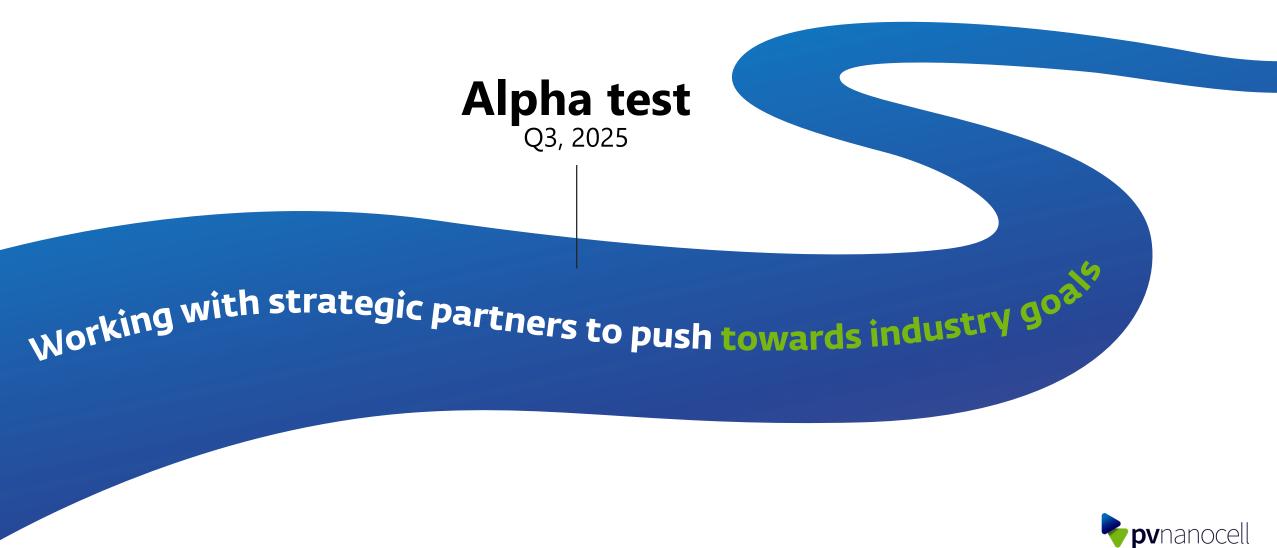




While copper-coated paste represents a step forward, it doesn't offer the same level of innovation and performance benefits as pure copper paste



Technology Roadmap



The adoption of copper-based solution is not a matter of if, but rather when



It's Feasible We Can Make it Happen



Our copper nanoparticles oxidation rate is slow and allows industrial mass production, printing, and module preparation time



Using laser sintering we achieve low resistivities and lines stable towards oxidation



Thank you

Would love to hear from you:

Cesar Manna , PhD VP R&D | VP Nano Cell

+972-543300265

🖂 cesar@pvnanocell.com

www.pvnanocell.com